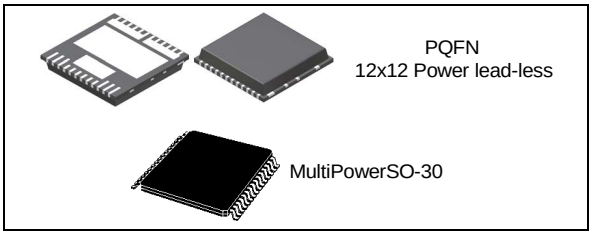
VND5004B-E
VND5004BSP30-E

Double 4mΩ high-side driver with analog current sense for automotive applications

Datasheet - production data



Features

Parameters	Symbol	Value
Max transient supply voltage	V_{CC}	41 V
Operating voltage range	V_{CC}	4.5 to 28 V
Max on-state resistance	R_{ON}	4 mΩ
Current limitation (typ)	I_{LIMH}	100 A
Off-state supply current	I_S	2 µA(1)

1. Typical value with all loads connected.

- General
  - Inrush current active management by power limitation
  - Very low standby current
  - 3.0 V CMOS compatible input
  - Optimized electromagnetic emission
  - Very low electromagnetic susceptibility
  - In compliance with the 2002/95/EC European directive
- Diagnostic functions
  - Proportional load current sense
  - Current sense disable
  - Thermal shutdown indication
- Protection
  - Undervoltage shutdown
  - Overvoltage clamp
  - Load current limitation
  - Thermal shutdown
  - Self limiting of fast thermal transients
  - Protection against loss of ground and loss of V_{CC}
  - Reverse battery protection with self switch on of the Power MOSFET
  - Electrostatic discharge protection application
- All types of resistive, inductive and capacitive loads
- Suitable for power management applications

Description

The VND5004BTR-E and VND5004BSP30-E are devices made using STMicroelectronics VIPower technology. They are intended for driving resistive or inductive loads with one side connected to ground. Active V_{CC} pin voltage clamp and load dump protection circuit protect the devices against transients on the Vcc pin. These devices integrate an analog current sense which delivers a current proportional to the load current (according to a known ratio) when CS_DIS is driven low or left open. When CS_DIS is driven high, the CURRENT SENSE pin is high impedance. Output current limitation protects the devices in overload condition. In case of long duration overload, the devices limit the dissipated power to a safe level up to thermal shutdown intervention. Thermal shutdown with automatic restart allows the device to recover normal operation as soon as a fault condition disappears.

Table 1. Devices summary

Package	Order codes		
	Tube	Tape and reel	Tray
PQFN-12x12 power lead-less	-	VND5004BTR-E	VND5004B-E
MultiPowerSO-30	VND5004BSP30-E	VND5004BSP30TR-E	-

This is information on a product in full production. www.st.com

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1 Block diagram and pin configurations

Figure 1. Block diagram

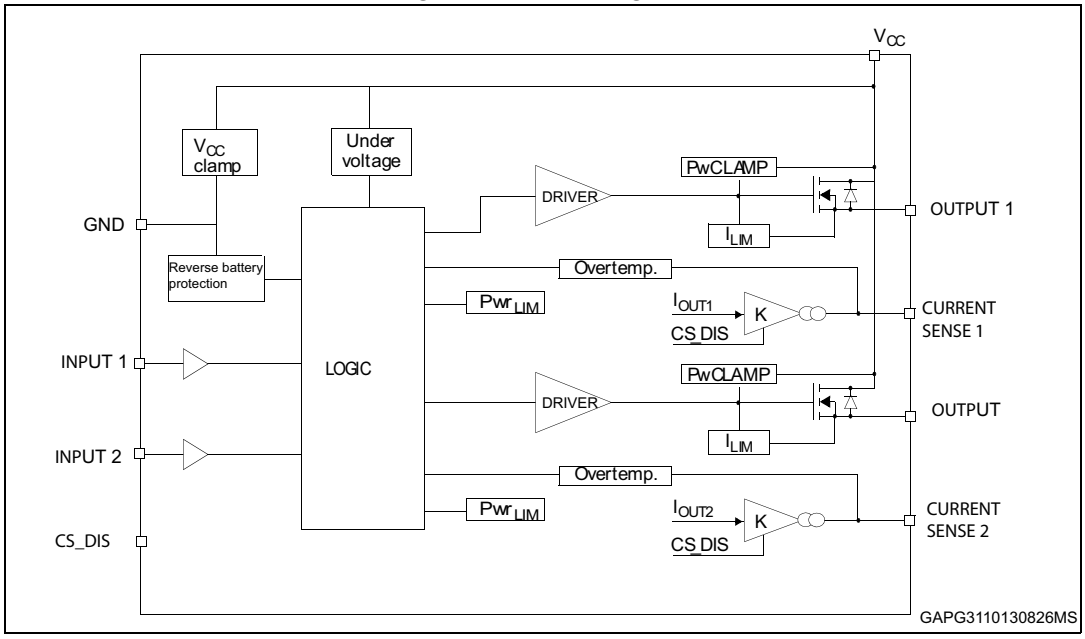


Table 2. Pin functions

Name	Function
V_{CC}	Battery connection
OUTPUT1,2	Power output
GND	Ground connection
INPUT1,2	Voltage controlled input pin with hysteresis, CMOS compatible. Controls output switch state
CURRENT SENSE1,2	Analog current sense pin, delivers a current proportional to the load current
CS_DIS	Active high CMOS compatible pin, to disable the current sense pins

Figure 2. Configuration diagram (not in scale)

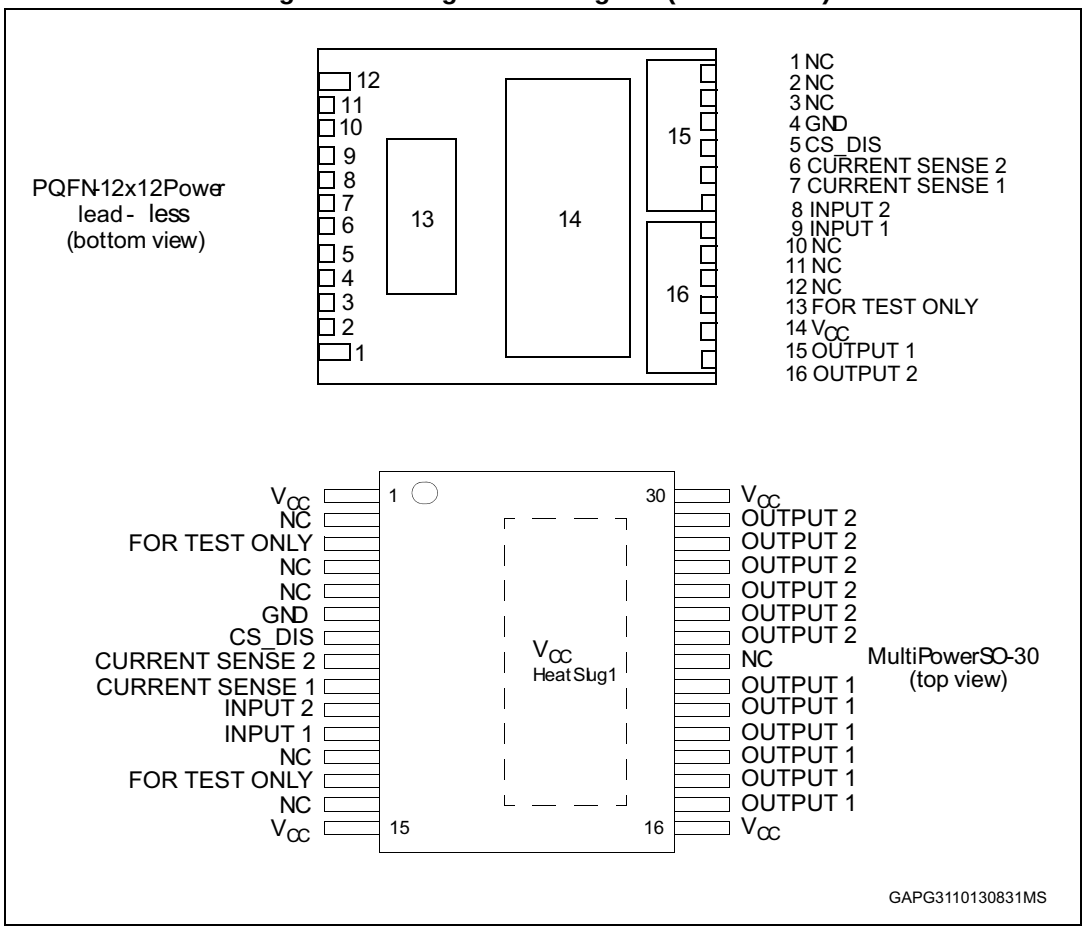
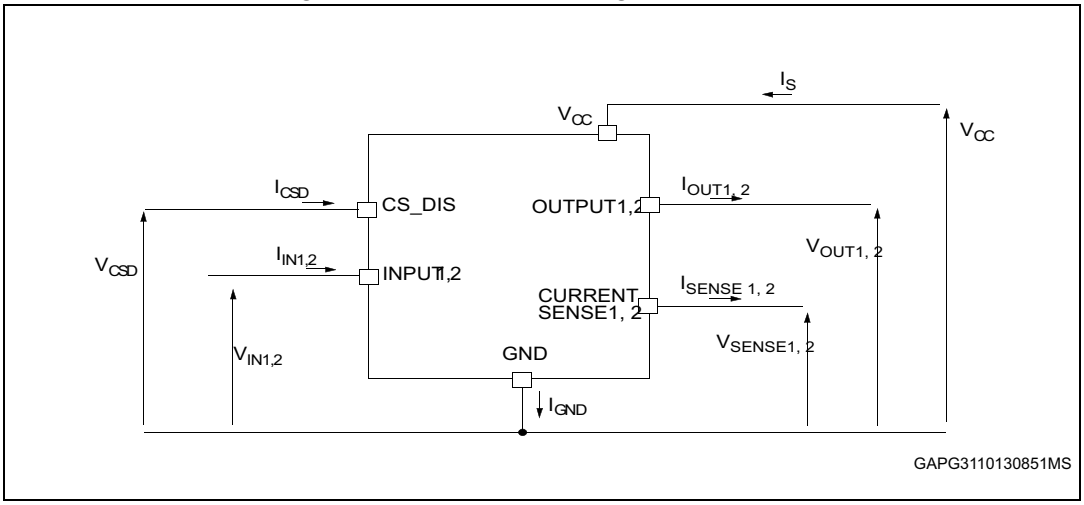


Table 3. Suggested connections for unused and not connected pins

Connection/pin	Current sense	N.C.	Output	Input	CS_DIS	For test only
Floating	Not allowed	X	X	X	X	X
To ground	Through 1 kΩ resistor	X	Not allowed	Through 10 kΩ resistor	Through 10 kΩ resistor	Not allowed

2 Electrical specifications

Figure 3. Current and voltage conventions



2.1 Absolute maximum ratings

Stress values that exceed those listed in the “Absolute maximum ratings” table can cause permanent damage to the device. These are stress ratings only, and operation of the device at these, or any other conditions greater than those, indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics sure program and other relevant quality documents.

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	DC supply voltage	28	V
V_{CCPK}	Transient supply voltage (T<400 ms, R_{load}>0.5 Ω)	41	V
$-V_{CC}$	Reverse DC supply voltage	16	V
I_{OUT}	DC output current	Internally limited	A
$-I_{OUT}$	Reverse DC output current	70	A
I_{IN}	DC input current	-1 to 10	mA
I_{CSD}	DC current sense disable input current	-1 to 10	mA
V_{CSENSE}	Current sense maximum voltage (V_{cc}>0 V)	Vcc-41 +V_{CC}	V V
E_{MAX}	Maximum switching energy (single pulse) (L=0.3 mH; R_L=0 Ω; V_{bat}=13.5 V; T_{jstart}=150 ºC; I_{OUT} = I_{limL}(typ.))	342	mJ
V_{ESD}	Electrostatic discharge (Human Body Model: R=1.5 kΩ; C=100 pF)	2000	V

Table 4. Absolute maximum ratings (continued)

Symbol	Parameter	Value	Unit
V_{ESD}	Charge device model (CDM-AEC-Q100-011)	750	V
T_j	Junction operating temperature	-40 to 150	°C
T_{STG}	Storage temperature	-55 to 150	°C

2.2 Thermal data

Table 5. Thermal data

Symbol	Parameter	Value		Unit
		MultiPowerSO-30	12x12 PLLP	
$R_{thj\text{-}case}$	Thermal resistance junction-case (MAX) (with one channel ON)	0.35	0.35	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient (MAX)	58(1)	39(2)	°C/W

1. PCB FR4 area 58 mmx58 mm, PCB thickness 2 mm, Cu thickness 35 µm, minimum pad layout.
2. PCB FR4 area 78 mmx78 mm, PCB thickness 2 mm, Cu thickness 35 µm, minimum pad layout.

2.3 Electrical characteristics

Values specified in this section are for 8 V<V_{CC}<24 V, -40 °C<T_j<150 °C, unless otherwise stated.

Table 6. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Power section						
V_{CC}	Operating supply voltage		4.5	13	28	V
V_{USD}	Undervoltage shutdown			3.5	4.5	V
$V_{USDhyst}$	Undervoltage shutdown hysteresis			0.5		V
R_{ON}	On-state resistance(1)	I_{OUT}=15 A; T_j=25 °C I_{OUT}=15 A; T_j=150 °C I_{OUT}=15 A; V_{CC}=5 V; T_j=25 °C			4 8 6	mΩ mΩ mΩ
$R_{ON\ REV}$	R_{dson} in reverse battery condition	V_{CC}=-13 V; I_{OUT}=-15 A; T_j=25 °C			4	mΩ
V_{clamp}	V_{CC} clamp voltage	I_{CC}=20 mA; $I_{OUT1,2}$=0 A	41	46	52	V
I_S	Supply current	Off-state; V_{CC}=13 V; T_j=25 °C; V_{IN}=V_{OUT}=V_{SENSE}=V_{CSD}=0 V On-state; V_{CC}=13 V; V_{IN}=5 V; I_{OUT}=0 A		 2(2) 3.5	 5(2) 6	 µA mA
$I_{L(off)}$	Off-state output current(1)	V_{IN}=V_{OUT}=0 V; V_{CC}=13 V; T_j=25 °C V_{IN}=V_{OUT}=0 V; V_{CC}=13 V; T_j=125 °C	0 0	0.01	3 5	µA
Switching (V_{CC} = 13V; T_j = 25°C)						
$t_{d(on)}$	Turn-on delay time	R_L= 0.87 Ω (see *Figure 5*)		25		µs
$t_{d(off)}$	Turn-on delay time	R_L= 0.87 Ω (see *Figure 5*)		35		µs
$(dV_{OUT}/dt)_{on}$	Turn-on voltage slope	R_L= 0.87 Ω		See *Figure 16*		V/µs
$(dV_{OUT}/dt)_{off}$	Turn-off voltage slope	R_L= 0.87 Ω		See *Figure 18*		V/µs
W_{ON}	Switching energy losses during t_{won}	R_L= 0.87 Ω (see *Figure 5*)		5.4		mJ
W_{OFF}	Switching energy losses during t_{woff}	R_L= 0.87 Ω (see *Figure 5*)		2.3		mJ
Logic inputs						
$V_{IL1,2}$	Input low level voltage				0.9	V
$I_{IL1,2}$	Low level input current	V_{IN}=0.9 V	1			µA
$V_{IH1,2}$	Input high level voltage		2.1			V

Table 6. Electrical characteristics (continued)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{IH1,2}$	High level input current	V_{IN}=2.1 V			10	µA
$V_{I(hyst)1,2}$	Input hysteresis voltage		0.25			V
$V_{ICL1,2}$	Input clamp voltage	I_{IN}=1 mA I_{IN}=-1 mA	5.5	 -0.7	7	V V
V_{CSDL}	CS_DIS low level voltage				0.9	V
I_{CSDL}	Low level CS_DIS current	V_{CSD}=0.9 V	1			µA
V_{CSDH}	CS_DIS high level voltage		2.1			V
I_{CSDH}	High level CS_DIS current	V_{CSD}=2.1 V			10	µA
$V_{CSD(hyst)}$	CS_DIS hysteresis voltage		0.25			V
V_{CSCL}	CS_DIS clamp voltage	I_{CSD}=1 mA I_{CSD}=-1 mA	5.5	 -0.7	7	V V
Protections and diagnostics (3)						
I_{limH}	Short circuit current	V_{CC}=13 V 5 V<V_{CC}<24 V	70	100	140 140	A A
I_{limL}	Short circuit current during thermal cycling	V_{CC}=13 V; T_R<T_j<T_{TSD}		40		A
T_{TSD}	Shutdown temperature		150	175	200	°C
T_R	Reset temperature		T_{RS}+1	T_{RS}+5		°C
T_{RS}	Thermal reset of STATUS		135			°C
T_{HYST}	Thermal hysteresis (T_{TSD}-T_R)			7		°C
V_{DEMAG}	Turn-off output voltage clamp	I_{OUT}=2 A; V_{IN}=0; L=6 mH	V_{CC}-28	V_{CC}-32	V_{CC}-35	V
Current sense (8 V<V_{CC}<16 V)						
K_0	I_{OUT}/I_{SENSE}	I_{OUT}=10 A; V_{SENSE}=4 V; V_{CSD}=0 V; T_j= -40 °C...150 °C T_j= 25 °C...150 °C	 7500 11000	 16000 16000	 23000 20900	
K_1	I_{OUT}/I_{SENSE}	I_{OUT}=15 A; V_{SENSE}=4 V; V_{CSD}=0 V; T_j= -40 °C...150 °C T_j= 25 °C...150 °C	 10300 12500	 16000 16000	 19500 19500	

Table 6. Electrical characteristics (continued)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
K_2	I_{OUT}/I_{SENSE}	I_{OUT}=30A; V_{SENSE}=4V; V_{CSD}=0V; T_j= -40°C...150°C T_j= 25°C...150°C	 12400 14000	 16500 16500	 19000 19000	
I_{SENSE0}	Analog sense current	I_{OUT}=0 A; V_{SENSE}=0 V; V_{CSD}=5 V; V_{IN}=0 V; T_j=-40 °C to 150 °C $V_{CS\ D}$=0 V; V_{IN}=5 V; T_j=-40 °C to 150°C	 0 0		 5 400	 µA µA
V_{SENSE}	Max analog sense output voltage	I_{OUT}=45 A; V_{CSD}=0 V; R_{SENSE}=3.9 kΩ	5			V
V_{SENSEH}	Analog sense output voltage in over temperature condition	V_{CC}=13 V; R_{SENSE}=3.9 kΩ		9		V
I_{SENSEH}	Analog sense output current in over temperature condition	Vcc=13 V; V_{SENSE}=5 V		8		mA
$t_{DSENSE1H}$	Delay response time from falling edge of CS_DIS pin	V_{SENSE}<4 V, 5 A<Iout<30 A I_{SENSE}=90% of $I_{SENSE\ max}$ (see *Figure 4*)		50	100	µs
$t_{DSENSE1L}$	Delay response time from rising edge of CS_DIS pin	V_{SENSE}<4V, 5A<Iout<30A I_{SENSE}=10% of $I_{SENSE\ max}$ (see *Figure 4*)		5	20	µs
$t_{DSENSE2H}$	Delay response time from rising edge of INPUT pin	V_{SENSE}<4V, 5A<Iout<30A I_{SENSE}=90% of $I_{SENSE\ max}$ (see *Figure 4*)		270	600	µs
$t_{DSENSE2L}$	Delay response time from falling edge of INPUT pin	V_{SENSE}<4V, 5A<Iout<30A I_{SENSE}=10% of $I_{SENSE\ max}$ (see *Figure 4*)		100	250	µs

1. For each channel.
2. PowerMOS leakage included.
3. To ensure long term reliability under heavy overload or short circuit conditions, protection and related diagnostic signals must be used together with a proper software strategy. If the device is subjected to abnormal conditions, this software must limit the duration and number of activation cycles.

Figure 4. Current sense delay characteristics

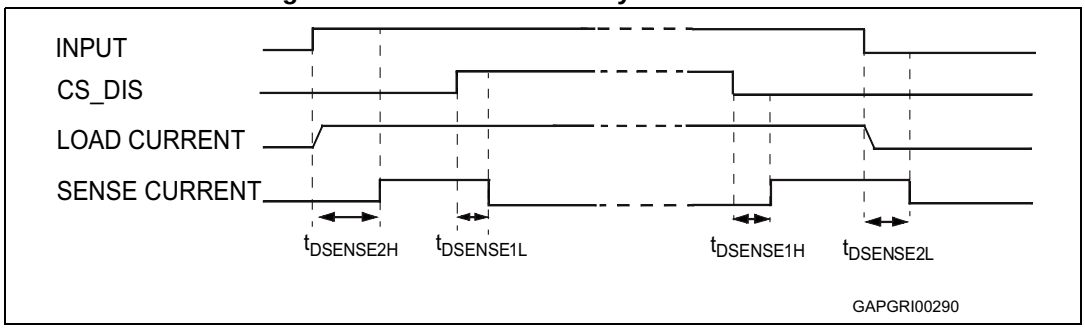


Figure 5. Switching characteristics

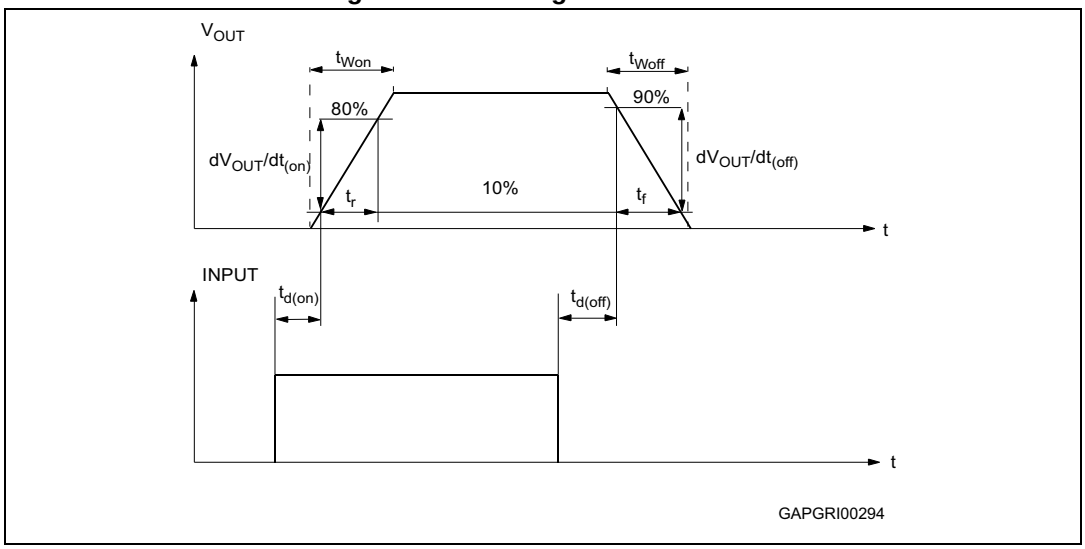


Table 7. Truth table

Conditions	$Input_n$	$Output_n$	SENSEn (V_{CSD}=0 V)(1) (see *Figure 4*)
Normal operation	L H	L H	0 Nominal
Over temperature	L H	L L	0 V_{SENSEH}
Undervoltage	L H	L L	0 0
Short circuit to GND ($R_{SC} \leq 10$ mΩ)	L H H	L L L	0 0 if $T_j < T_{TSD}$ V_{SENSEH} if $T_j > T_{TSD}$
Short circuit to V_{CC}	L H	H H	0 < Nominal
Negative output voltage clamp	L	L	0

1. If V_{CSD} is high, the SENSE output is at a high impedance. Its potential depends on leakage currents and the external circuit.

Table 8. Electrical transient requirements (part 1/3)

ISO 7637-2: 2004(E) test pulse	Test levels(1)		Number of pulses or test times	Burst cycle/pulse repetition time		Delays and impedance
	III	IV				
1	-75 V	-100 V	5000 pulses	0.5 s	5 s	2 ms, 10 Ω
2a	+37 V	+50 V	5000 pulses	0.2 s	5 s	50 µs, 2 Ω
3a	-100 V	-150 V	1h	90 ms	100 ms	0.1 µs, 50 Ω
3b	+75 V	+100 V	1h	90 ms	100 ms	0.1 µs, 50 Ω
4	-6 V	-7 V	1 pulse			100 ms, 0.01 Ω
5b(2)	+65 V	+87 V	1 pulse			400 ms, 2 Ω

1. The above test levels must be considered referred to V_{CC} = 13.5 V except for pulse 5b.
2. Valid in case of external load dump clamp: 40V maximum referred to ground. The protection strategy allows PowerMOS to be cyclically switched on during load dump, so distributing the load dump energy along the time and to transfer a part of it to the load.

Table 9. Electrical transient requirements (part 2/3)

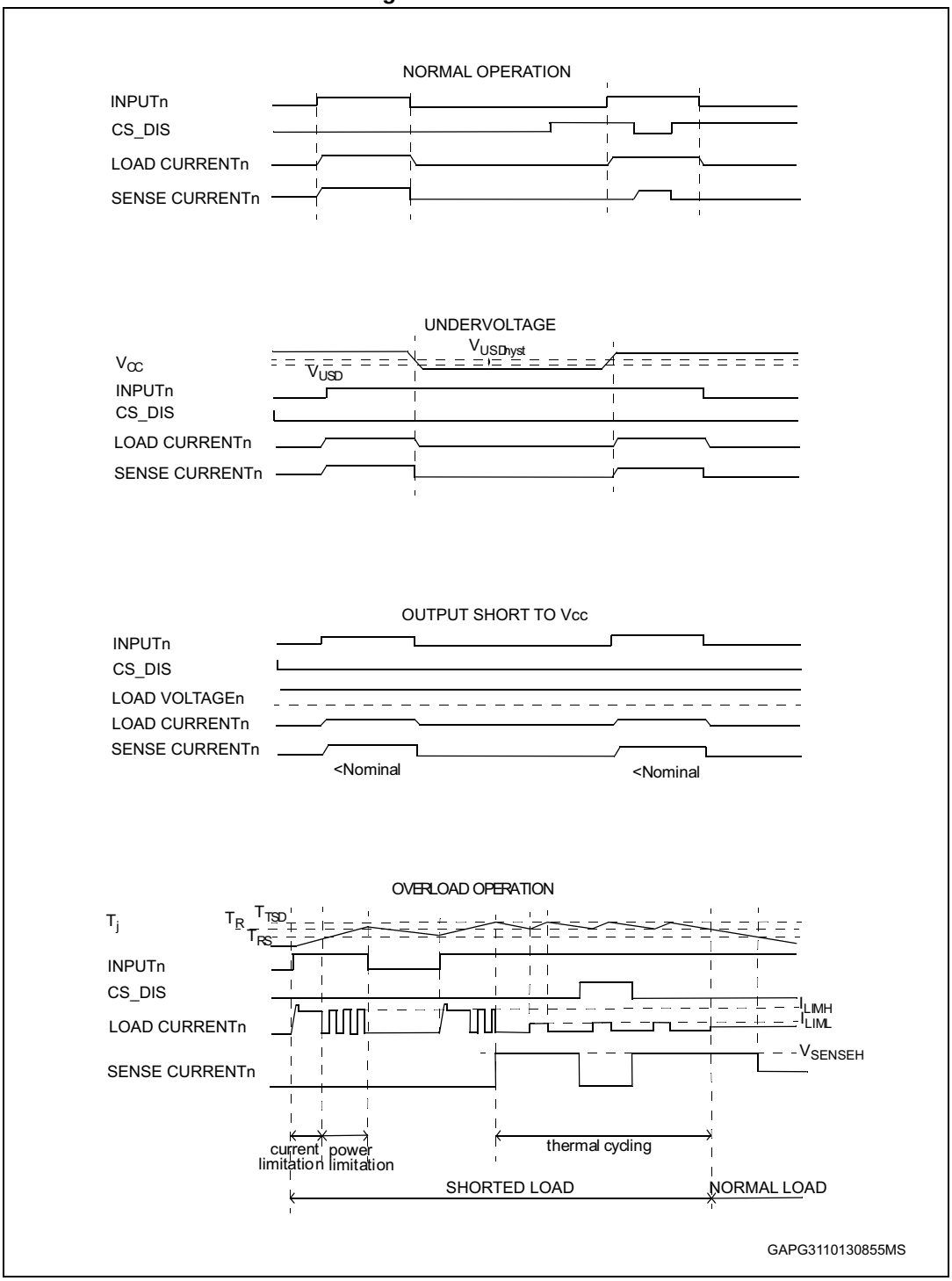
ISO 7637-2: 2004(E) test pulse	Test level results(1)	
	III	IV
1	C	C
2a	C	C
3a	C	C
3b	C	C
4	C	C
5b(2) (3)	C	C

1. The above test levels must be considered referred to V_{CC} = 13.5 V except for pulse 5b.
2. Valid in case of external load dump clamp: 40V maximum referred to ground. The protection strategy allows PowerMOS to be cyclically switched on during load dump, so distributing the load dump energy along the time and to transfer a part of it to the load.
3. Suppressed load dump (pulse 5b) is withstood with a minimum load connected as specified in *Table 4.: Absolute maximum ratings*.

Table 10. Electrical transient requirements (part 3/3)

Class	Contents
C	All functions of the device are performed as designed after exposure to disturbance.
E	One or more functions of the device are not performed as designed after exposure to disturbance and cannot be returned to proper operation without replacing the device.

Figure 6. Waveforms



2.4 Electrical characteristics curves

Figure 7. Off-state output current

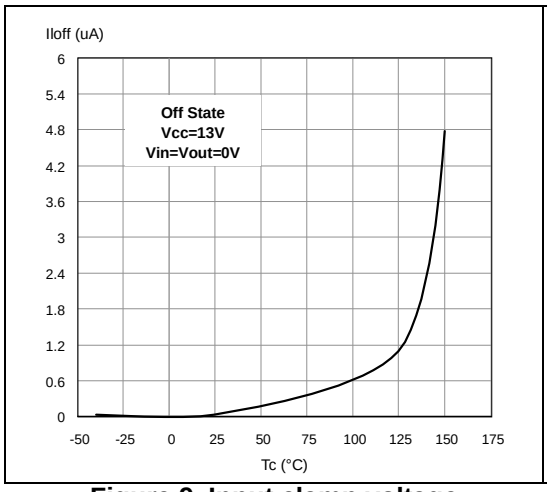


Figure 8. High level input current

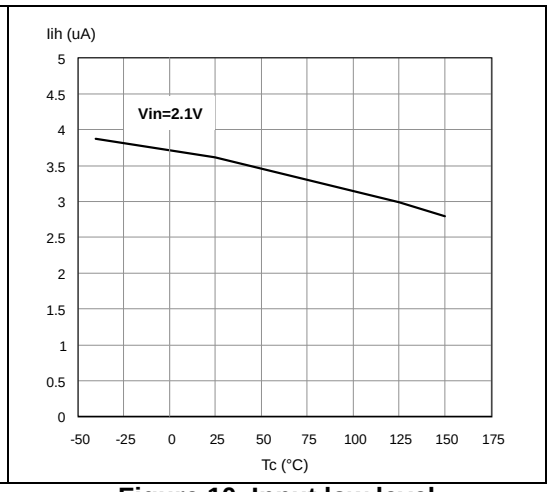


Figure 9. Input clamp voltage

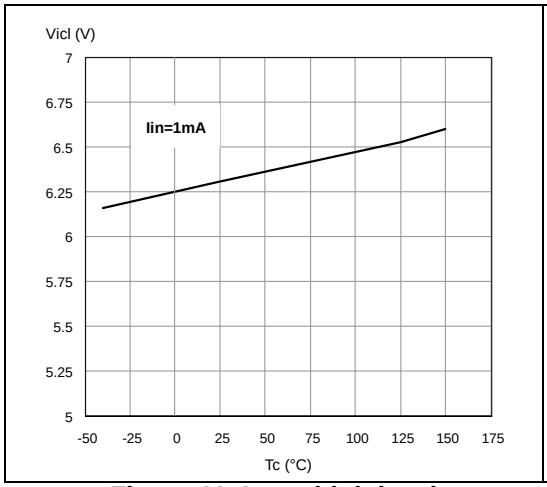


Figure 10. Input low level

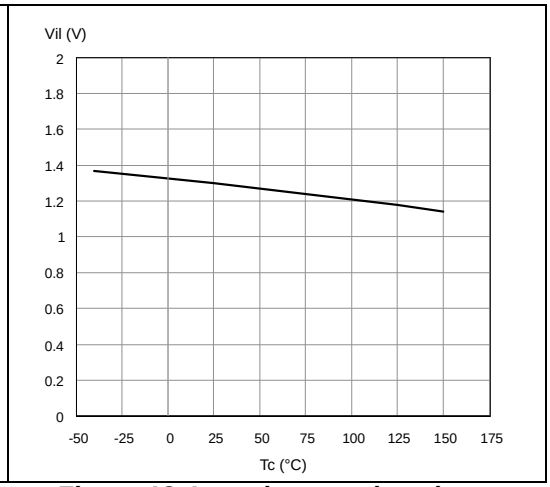


Figure 11. Input high level

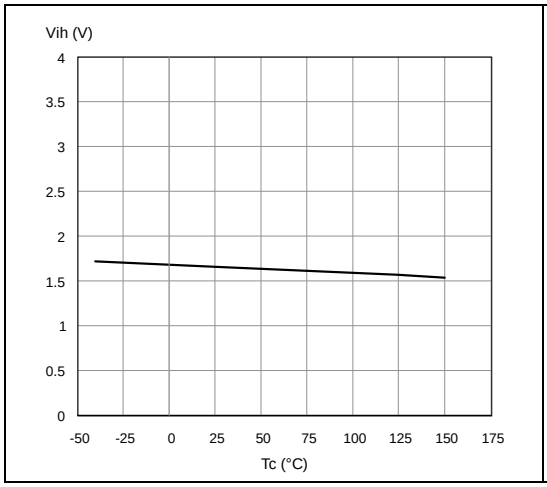


Figure 12. Input hysteresis voltage

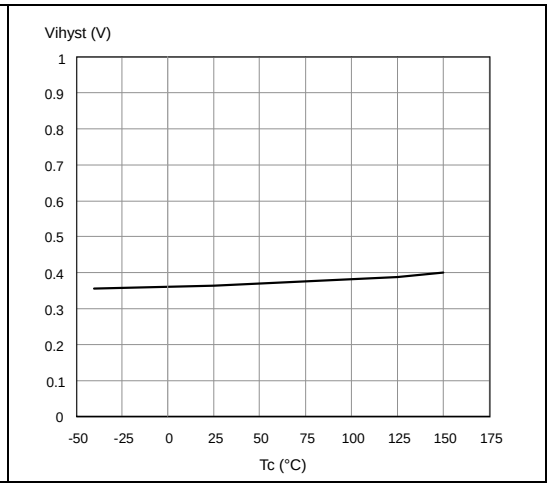


Figure 13. On-state resistance vs T_{case}

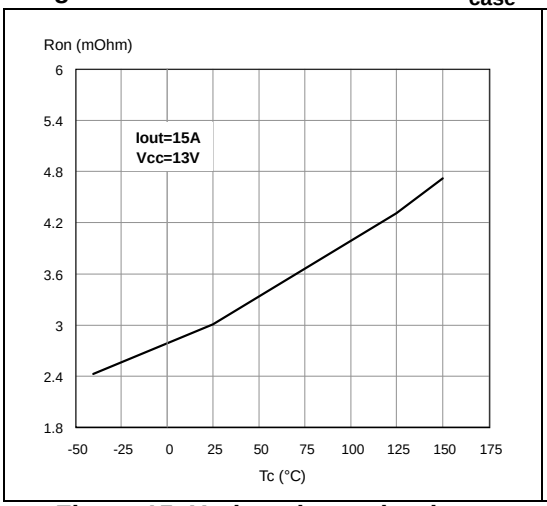


Figure 14. On-state resistance vs V_{CC}

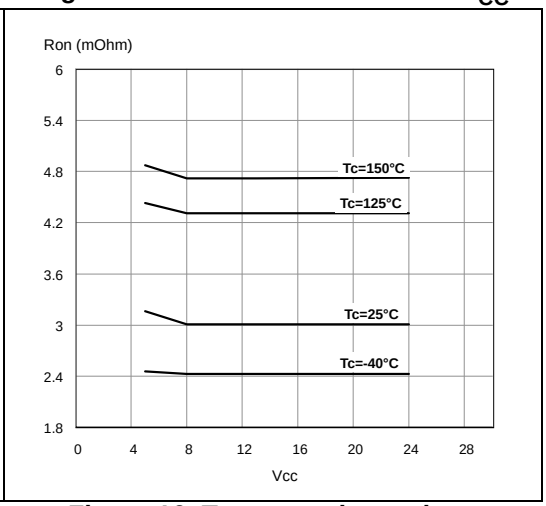


Figure 15. Undervoltage shutdown

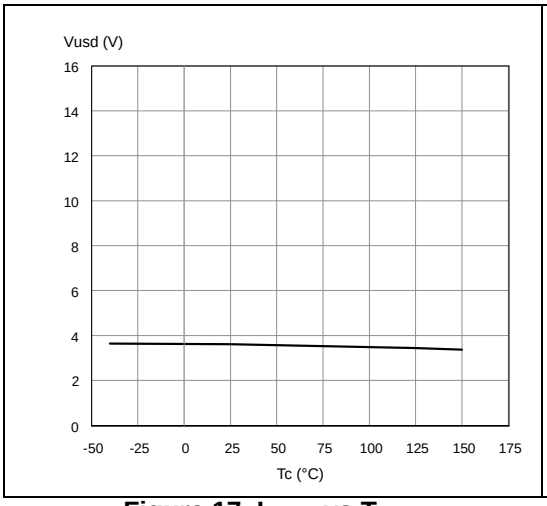


Figure 16. Turn-on voltage slope

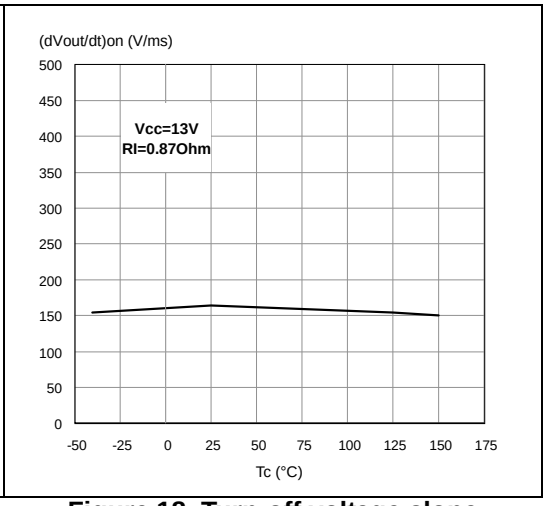


Figure 17. I_{LIMH} vs T_{case}

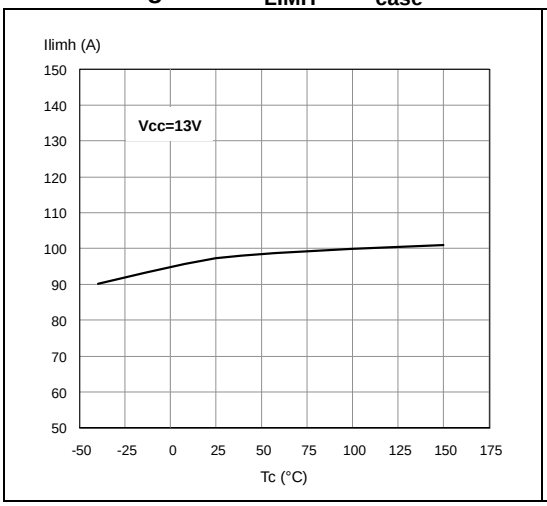


Figure 18. Turn-off voltage slope

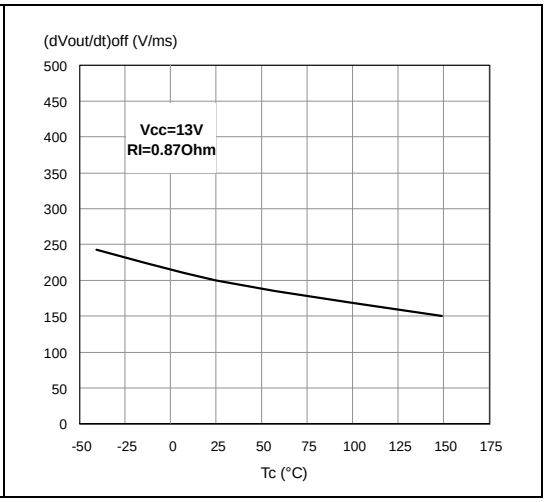


Figure 19. CS_DIS high level voltage

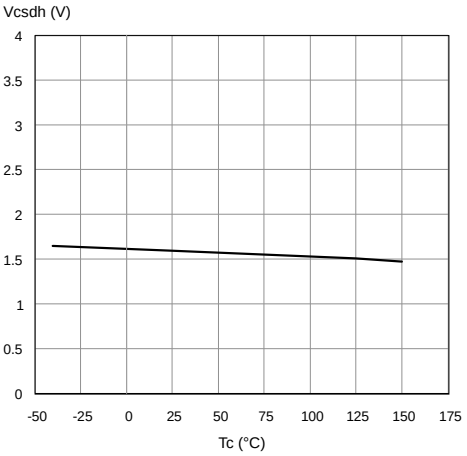


Figure 20. CS_DIS clamp voltage

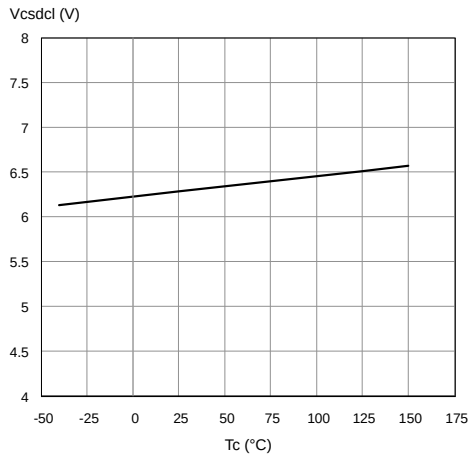
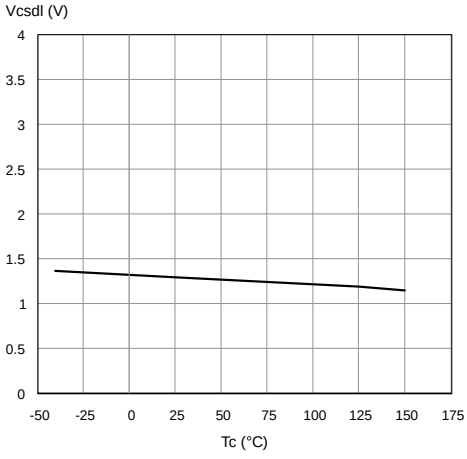
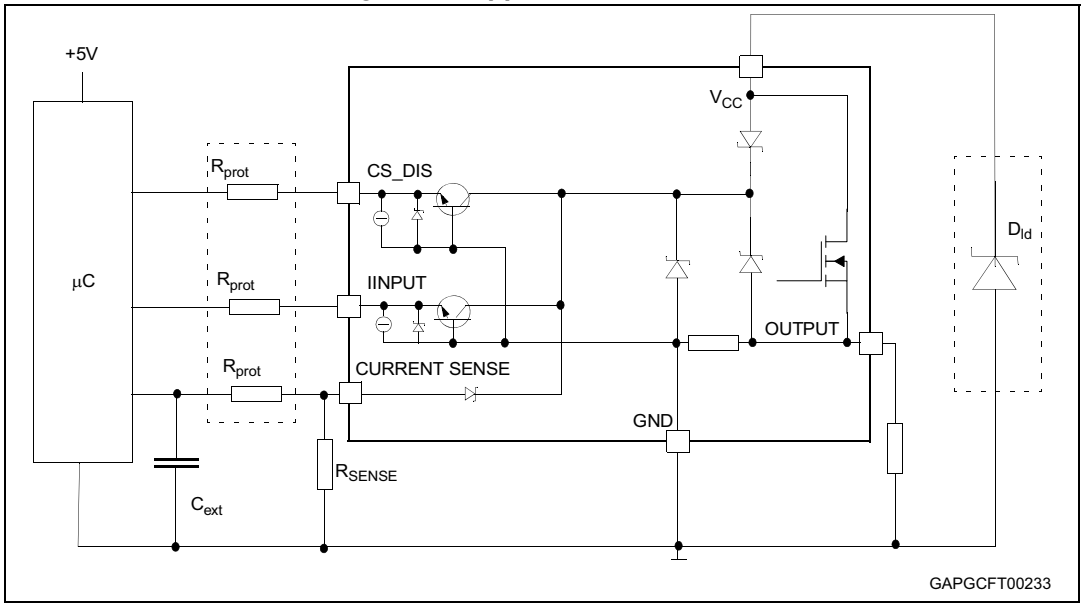


Figure 21. CS_DIS low level voltage



3 Application information

Figure 22. Application schematic



3.1 Microcontroller I/Os protection

When negative transients are present on the V_{CC} line, the control pins will be pulled negative to approximately -1.5 V.

ST suggests the insertion of resistors (R_{prot}) in the lines to prevent the µC I/Os pins from latching up.

The values of these resistors provide a compromise between the leakage current of the µC, the current required by the HSD I/Os (input levels compatibility) and the latch-up limit of the µC I/Os.

$-V_{CCpeak}/I_{latchup} \leq R_{prot} \leq (V_{OH\mu C}-V_{IH}) / I_{IHmax}$

Calculation example:

For V_{CCpeak}= - 1.5 V and $I_{latchup} \geq$ 20 mA; $V_{OH\mu C} \geq$ 4.5 V

75 Ω ≤ R_{prot} ≤ 240 kΩ.

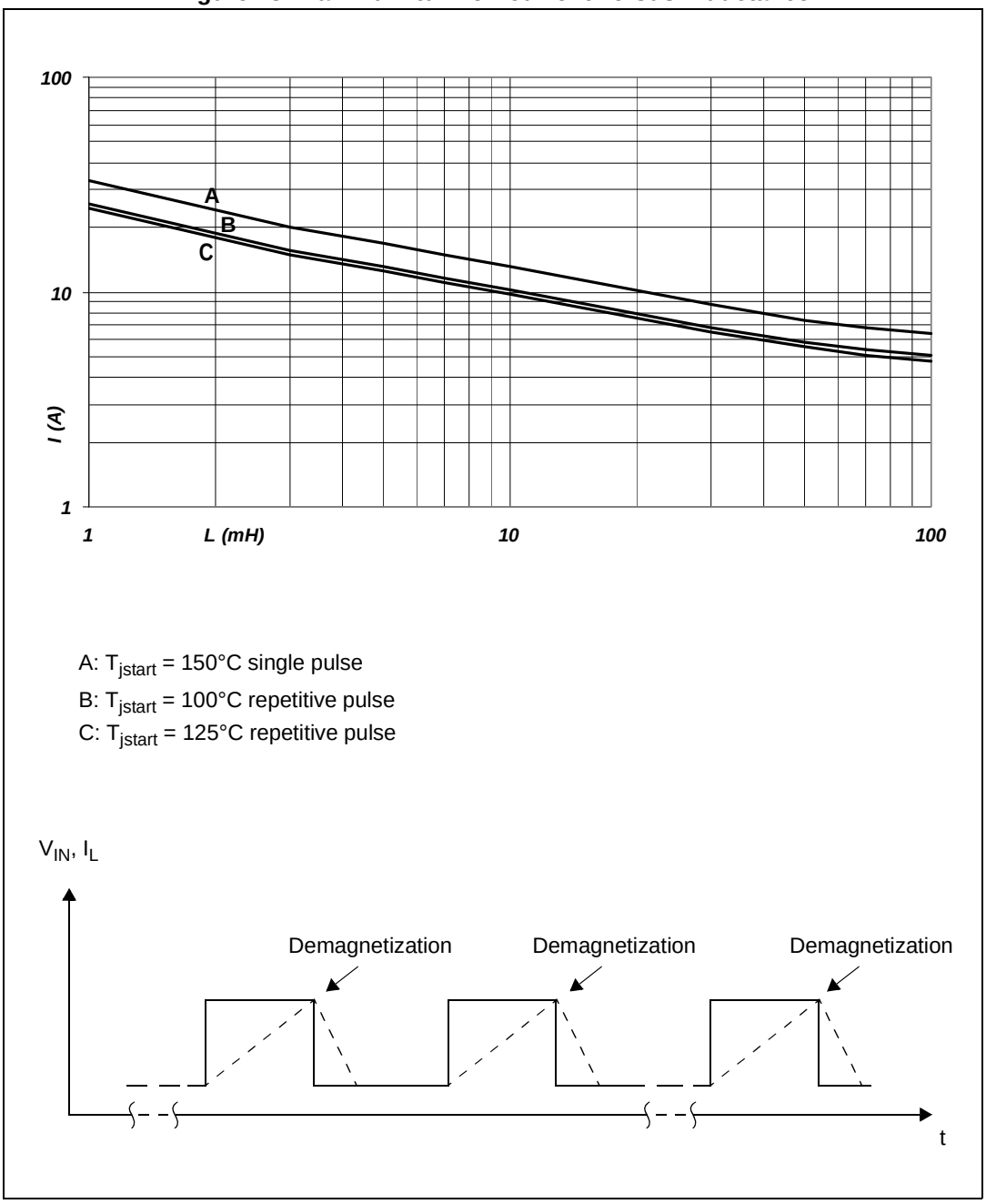
Recommended values: R_{prot} =10 kΩ, C_{EXT}=10 nF

3.2 Load dump protection

D_{ld} is necessary (voltage transient suppressor) if the load dump peak voltage exceeds the V_{CCPK} max rating. The same applies if the device will be subject to transients on the V_{CC} line that are greater than the ones shown in the ISO 7637-2: 2004(E) table.

3.3 Maximum demagnetization energy (V_{CC} = 13.5 V)

Figure 23. Maximum turn-off current versus inductance



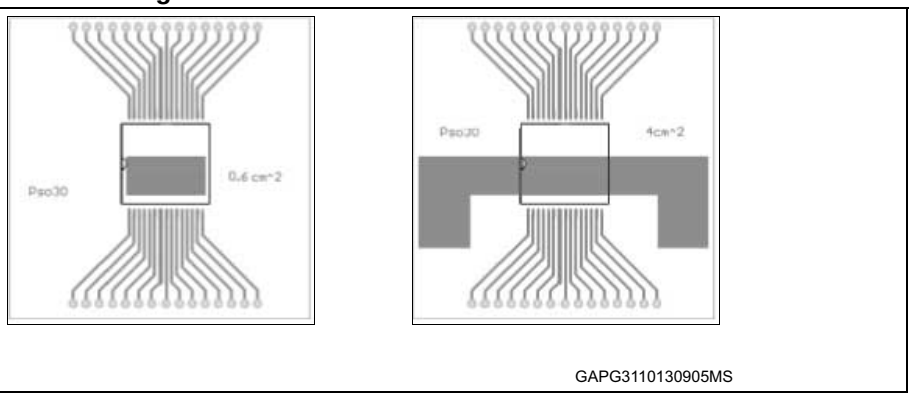
Note: Values are generated with R_L = 0 Ω.

In case of repetitive pulses, T_{jstart} (at beginning of each demagnetization) of every pulse must not exceed the temperature specified above for curves A and B.

4 Package and PC board thermal data

4.1 MultiPowerSO-30 thermal data

Figure 24. MultiPowerSO-30 PC board



Note: Layout condition of R_{th} and Z_{th} measurements (PCB: Double layer, Thermal Vias, FR4 area= 58 mm x 58 mm, PCB thickness=2 mm, Cu thickness=70 µm (front and back side), Copper areas: from minimum pad lay-out to 4 cm^2).

Figure 25. $R_{thj\text{-}amb}$ vs PCB copper area in open box free air condition (one channel on)

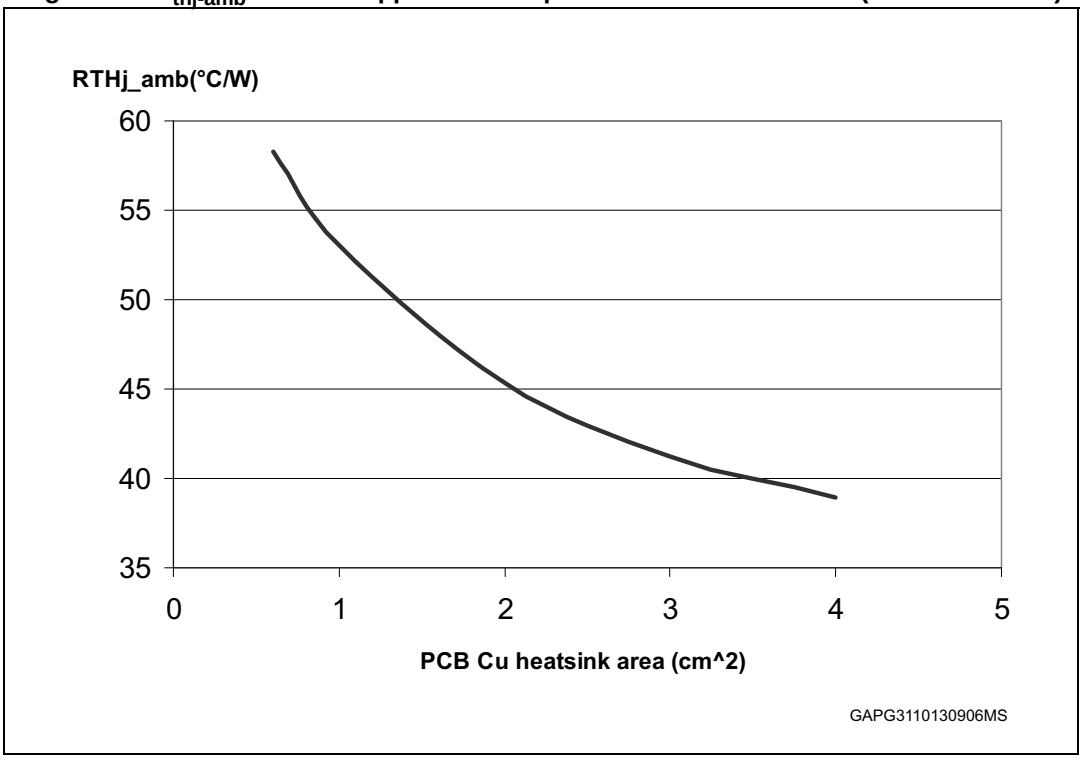


Figure 26. MultiPowerSO-30 thermal impedance junction ambient single pulse (one channel on)

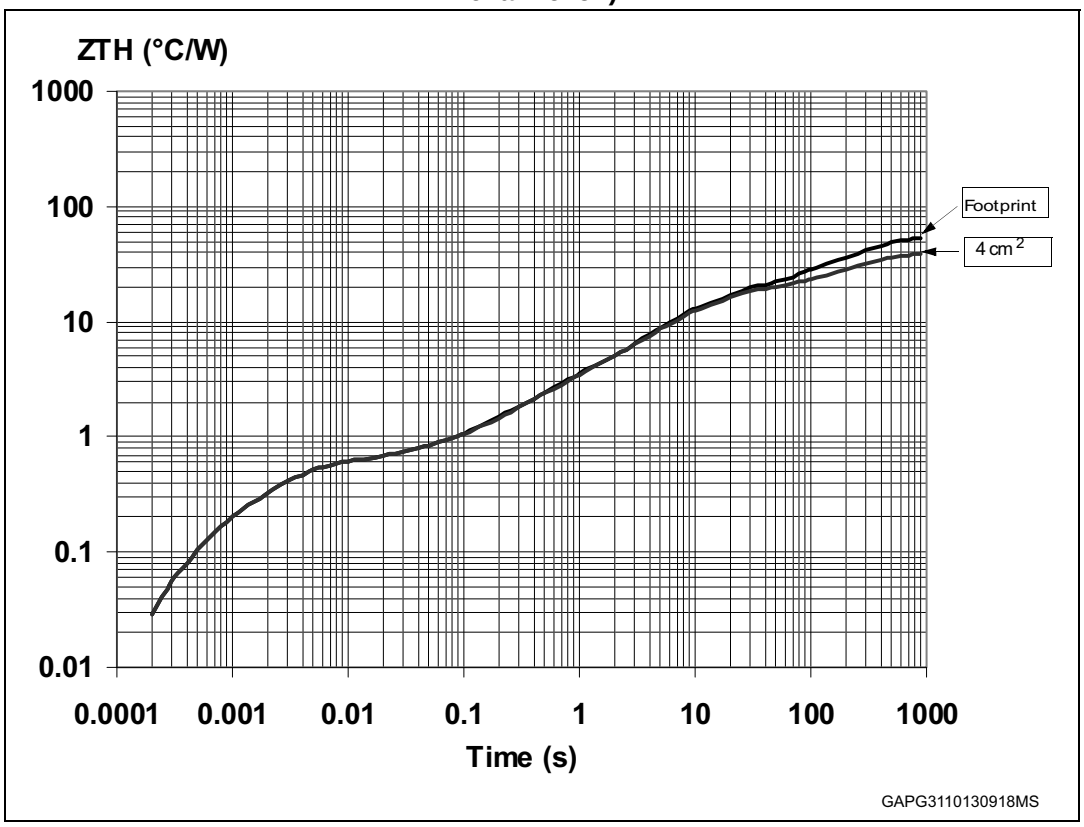
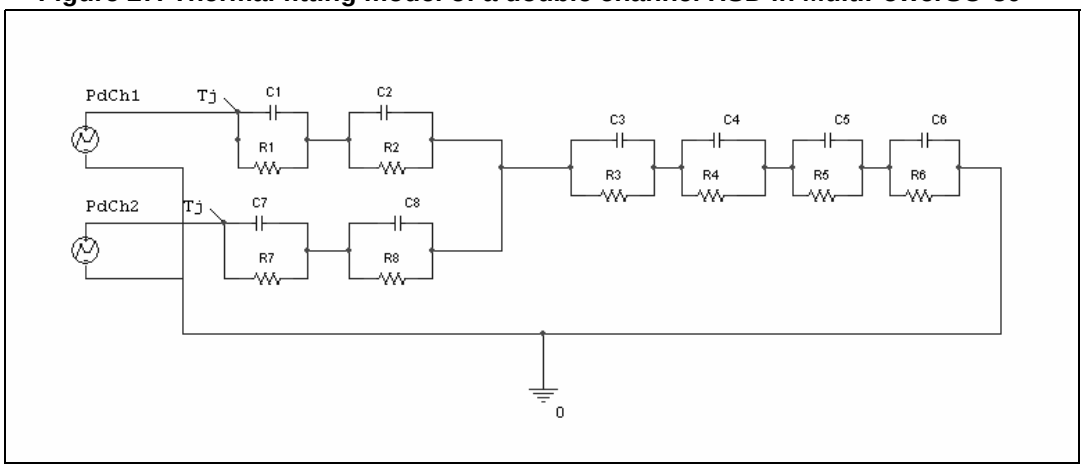


Figure 27. Thermal fitting model of a double channel HSD in MultiPowerSO-30[(a)]



a. The fitting model is a simplified thermal tool and is valid for transient evolutions where the embedded protections (power limitation or thermal cycling during thermal shutdown) are not triggered.

Equation 1: pulse calculation formula

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp}(1 - \delta)$$

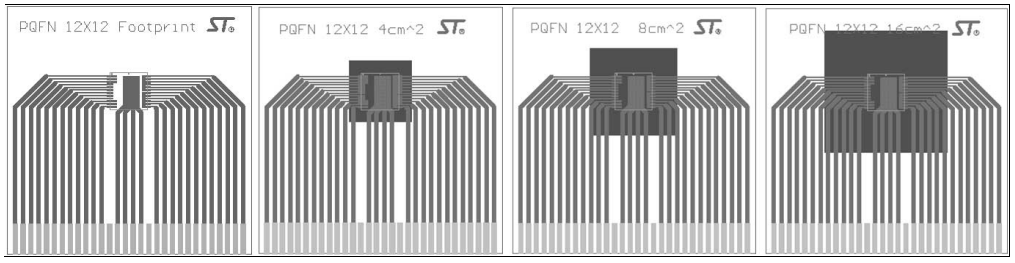
where $\delta = t_P/T$

Table 11. Thermal parameters for MultiPowerSO-30

Area/island (cm^2)	Footprint	4
R1 (°C/W)	0.05	
R2 (°C/W)	0.3	
R3 (°C/W)	0.5	
R4 (°C/W)	1.3	
R5 (°C/W)	14	
R6 (°C/W)	44.7	23.7
R7 (°C/W)	0.05	
R8 (°C/W)	0.3	
C1 (W.s/°C)	0.005	
C2 (W.s/°C)	0.008	
C3 (W.s/°C)	0.01	
C4 (W.s/°C)	0.3	
C5 (W.s/°C)	0.6	
C6 (W.s/°C)	5	11
C7 (W.s/°C)	0.005	
C8 (W.s/°C)	0.008	

4.2 PQFN - 12x12 power lead-less thermal data

Figure 28. 12x12 Power lead-less package PC board



Note: Layout condition of R_{th} and Z_{th} measurements (PCB: Double layer, Thermal Vias, FR4 area= 78 mm x 78 mm, PCB thickness=2mm, Cu thickness=70 µm (front and back side), Copper areas: from minimum pad lay-out to 16 cm^2).

Figure 29. $R_{thj-amb}$ vs PCB copper area in open box free air condition (one channel on)

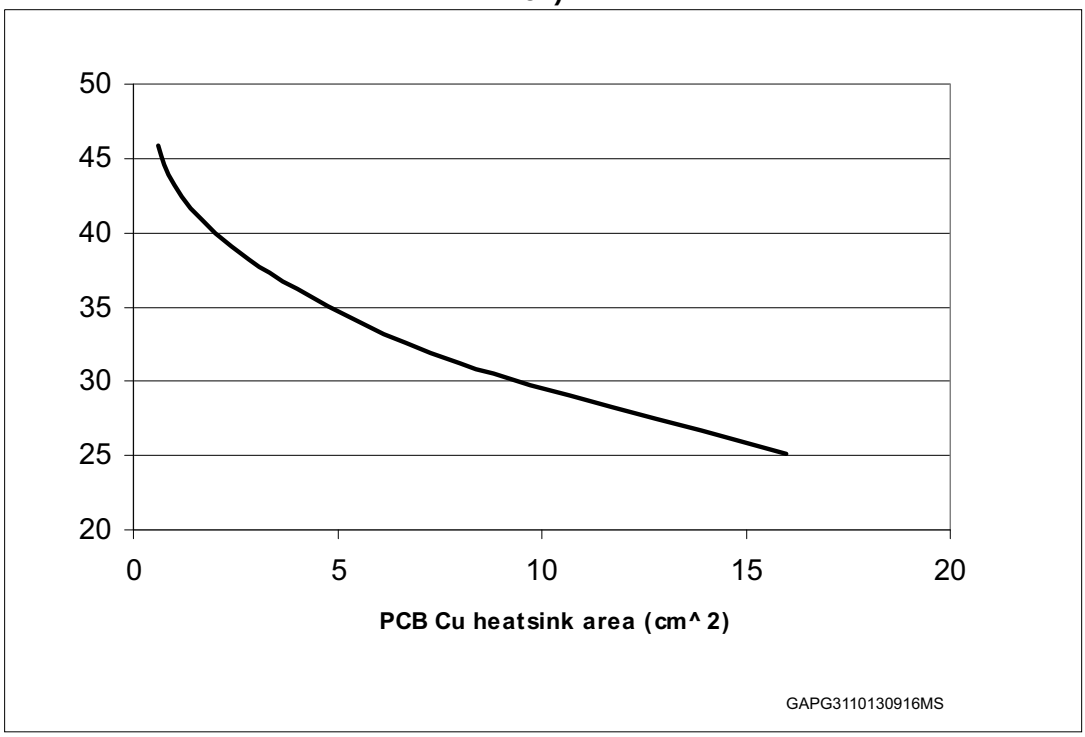


Figure 30. PQFN - 12x12 power lead-less package thermal impedance junction ambient single pulse (one channel on)

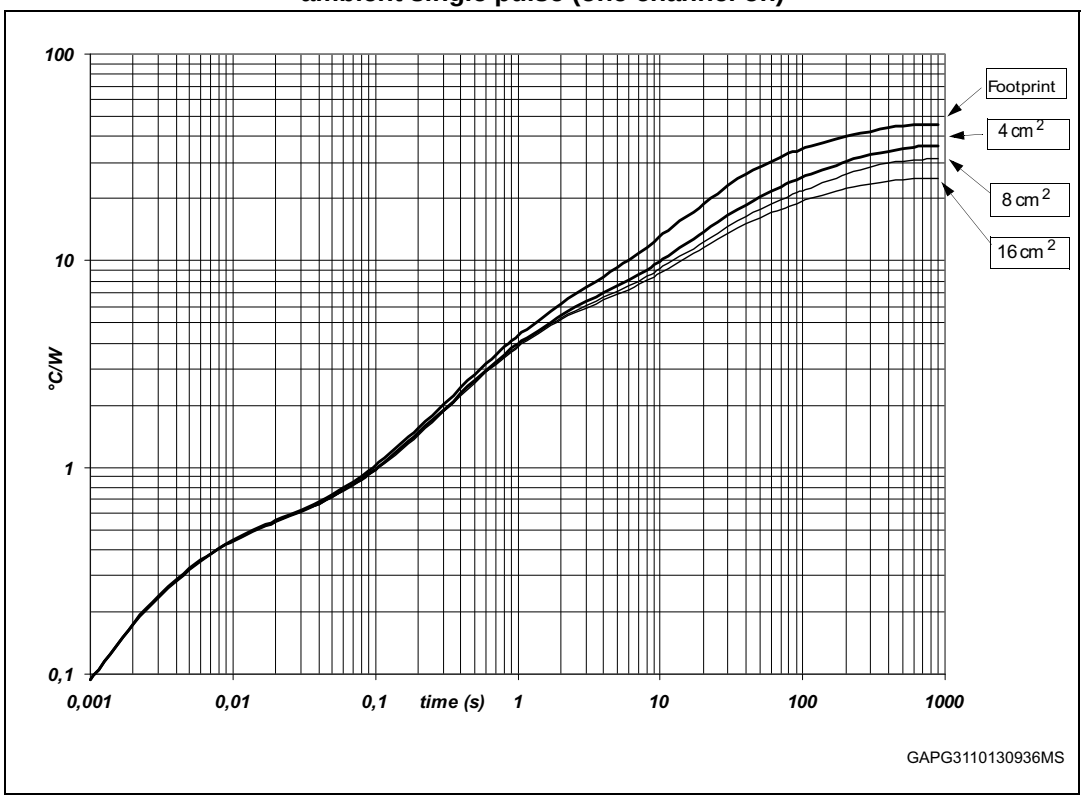
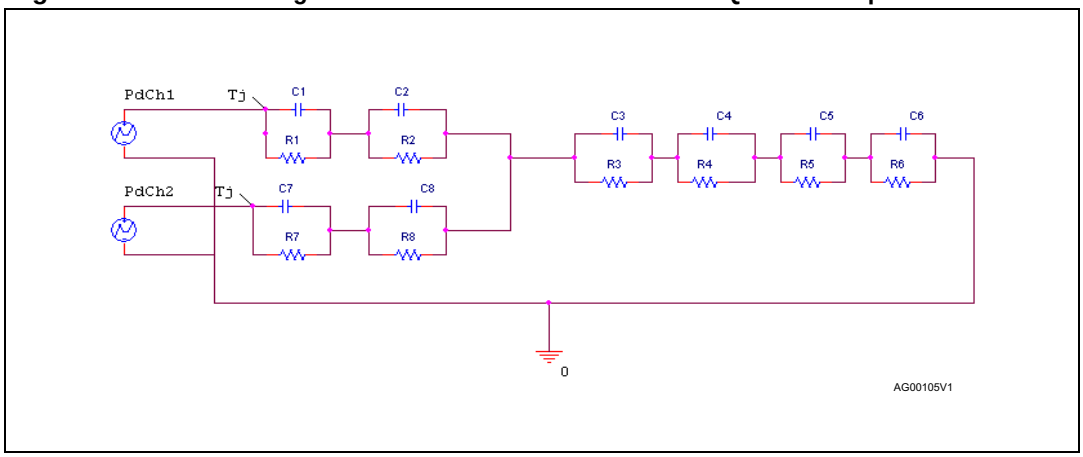


Figure 31. Thermal fitting model of a double channel HSD in PQFN - 12x12 power lead-less(b)



Equation 2: pulse calculation formula

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp}(1-\delta)$$

where $\delta = t_P/T$

Table 12. Thermal parameters for PQFN - 12x12 power lead-less

Area/island (cm^2)	Footprint	4	8	16
R1 (°C/W)	0.3			
R2 (°C/W)	0.15			
R3 (°C/W)	4.2			
R4 (°C/W)	9.6	9.4	9.2	9
R5 (°C/W)	15.1	10.5	8.5	5.5
R6 (°C/W)	16.7	12	9	6
R7 (°C/W)	0.3			
R8 (°C/W)	0.15			
C1 (W.s/°C)	0.021			
C2 (W.s/°C)	0.015			
C3 (W.s/°C)	0.2			
C4 (W.s/°C)	1.9	2.2	2.32	2.45
C5 (W.s/°C)	2.45	7.3	13.7	20
C6 (W.s/°C)	11.85	22	25	30
C7 (W.s/°C)	0.021			
C8 (W.s/°C)	0.015			

b. The fitting model is a simplified thermal tool and is valid for transient evolutions where the embedded protections (power limitation or thermal cycling during thermal shutdown) are not triggered.

5 Package and packing information

5.1 ECOPACK® packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*.

ECOPACK® is an ST trademark.

5.2 MultiPowerSO-30 mechanical data

Figure 32. MultiPowerSO-30 outline

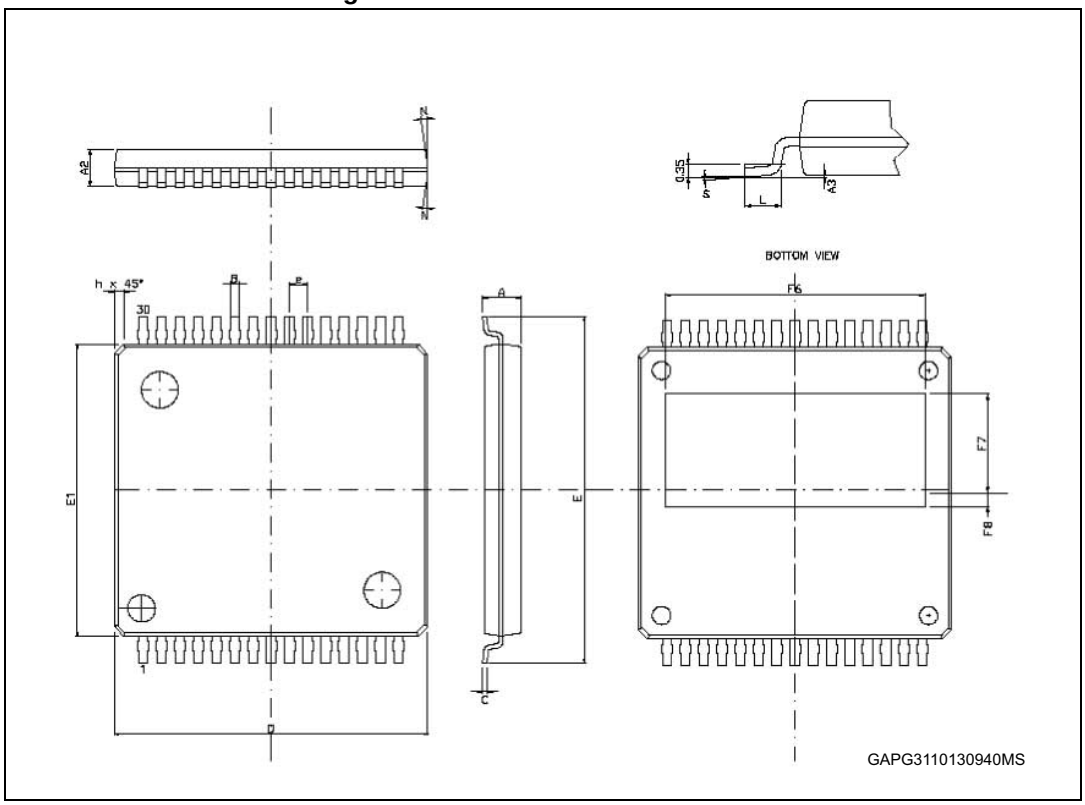


Table 13. MultiPowerSO-30 mechanical data

Symbol	Millimeters		
	Min.	Typ.	Max.
A			2.35
A2	1.85		2.25
A3	0		0.1
B	0.42		0.58
C	0.23		0.32
D	17.1	17.2	17.3
E	18.85		19.15
E1	15.9	16	16.1
“e”	1		
F6		14.3	
F7		5.45	
F8		0.73	
L	0.8		1.15
N			10 Deg
S	0 Deg		7 Deg

5.3 PQFN - 12x12 power lead-less mechanical data

Figure 33. PQFN - 12x12 power lead-less outline

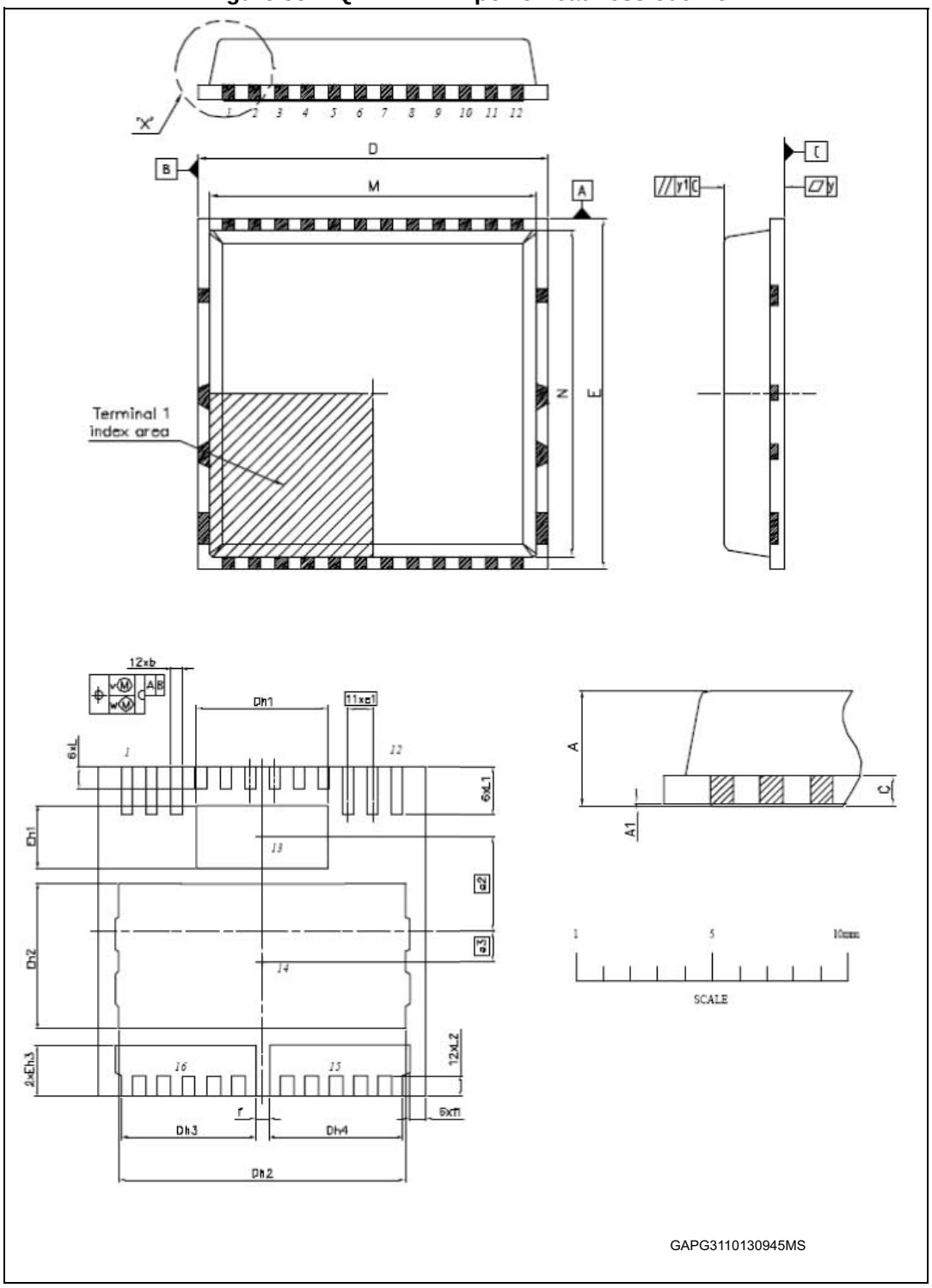


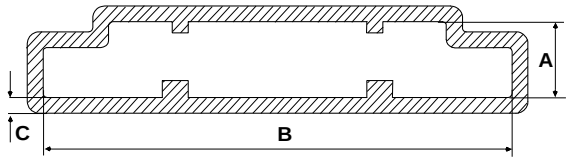
Table 14. PQFN - 12x12 power lead-less mechanical data

Symbol	Millimeters		
	Min.	Typ.	Max.
A	2		2.2
A1	0		0.05
b	0.35		0.47
C		0.50	
D	11.90		12.10
Dh1	4.65		4.95
Dh2	10.45		10.65
Dh3	4.80		5
Dh4	4.80		5
E	11.90		12.10
Eh1	2.15		2.45
Eh2	5.15		5.45
Eh3	1.70		2
e1		0.90	
e2		3.45	
e3		1.10	
f		0.50	
f1		0.60	
L	0.75		0.95
L1	1.65		1.90
L2	0.76		0.78
M	11.10		11.30
N	11.10		11.30
v		0.1	
w		0.05	
y		0.05	
y1		0.1	

5.4 MultiPowerSO-30 packing information

The devices can be packed in tube or tape and reel shipments (see the *Table 1: Devices summary* for packaging quantities).

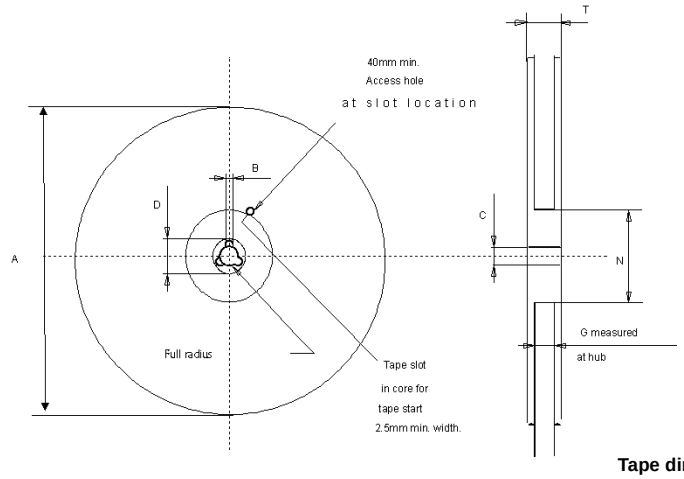
Figure 34. MultiPowerSO-30 tube shipment (no suffix)



Tube dimension

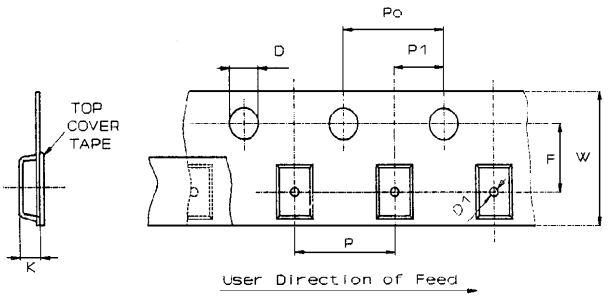
Dimension	mm
Base Q.ty	29
Bulk Q.ty	435
Tube length (± 0.5)	532
A	3.82
B	23.6
C (± 0.13)	0.8

Figure 35. MultiPowerSO-30 tape and reel shipment (suffix “TR”)



Reel dimension

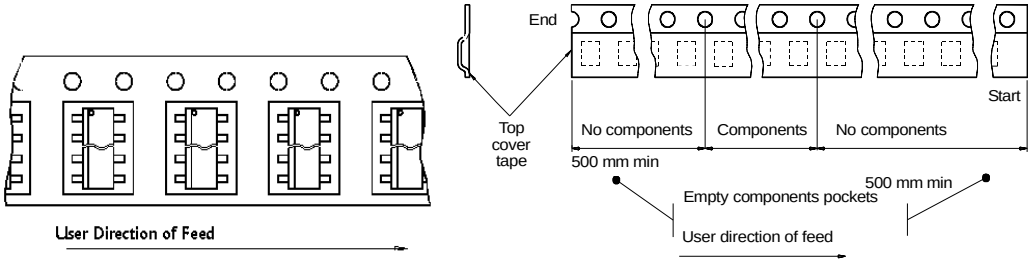
Dimension	mm
Base Q.ty	1000
Bulk Q.ty	1000
A (max)	330
B (min)	1.5
C (± 0.2)	13
D (min)	20.2
G (+ 2 / -0)	32
N (min)	100
T (max)	38.4



Tape dimensions

According to Electronic Industries Association (EIA) Standard 481 rev. A, Feb 1986

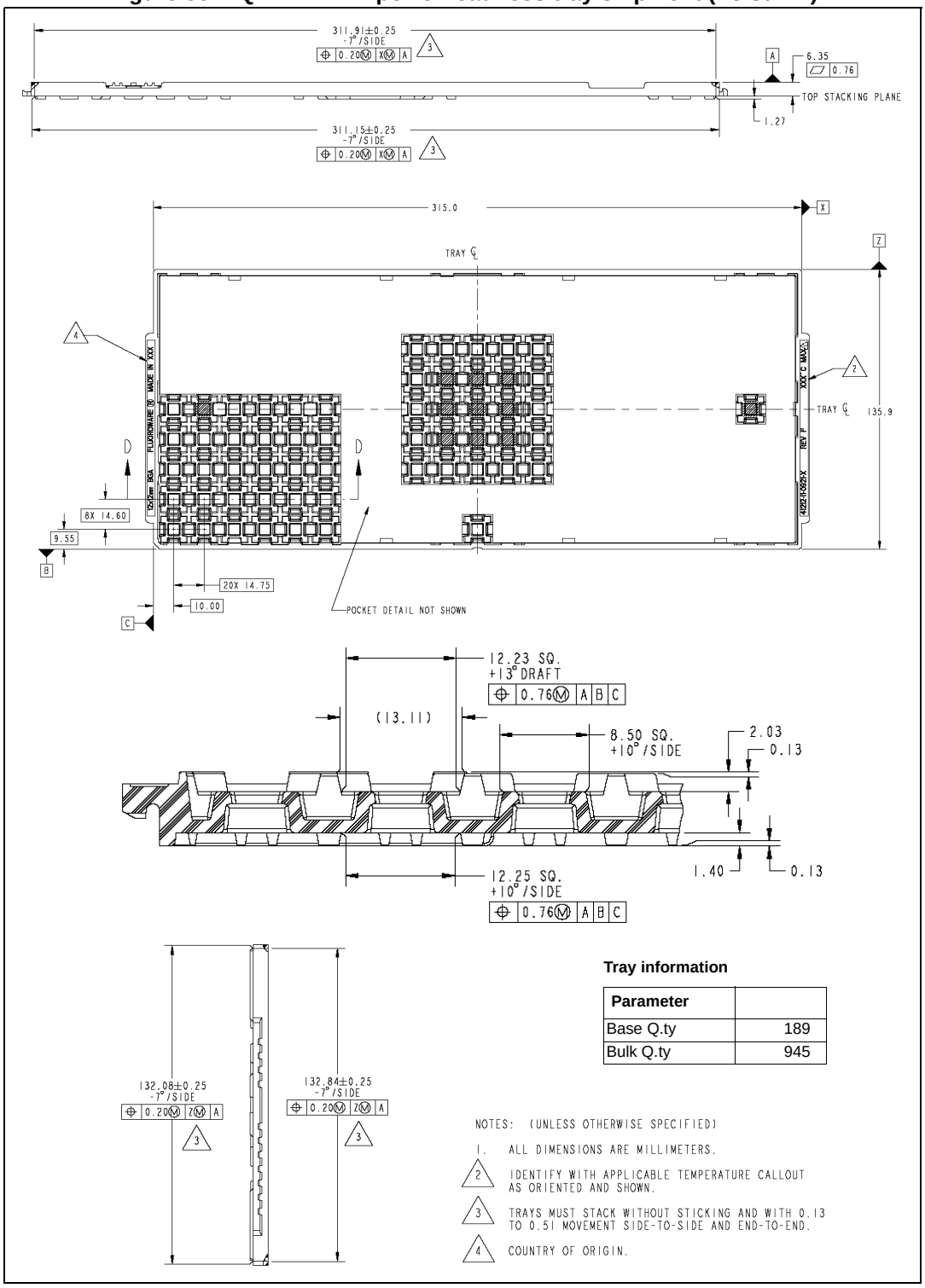
Description	Dimension	mm
Tape width	W	32
Tape Hole Spacing	P0 (± 0.1)	4
Component Spacing	P	24
Hole Diameter	D (± 0.1/-0)	1.5
Hole Diameter	D1 (min)	2
Hole Position	F (± 0.1)	14.2
Compartment Depth	K (max)	2.2
Hole Spacing	P1 (± 0.1)	2



5.5 PQFN - 12x12 power lead-less packing information

The devices can be packed in tray or tape and reel shipments (see the *Table 1: Devices summary* for packaging quantities).

Figure 36. PQFN - 12x12 power lead-less tray shipment (no suffix)



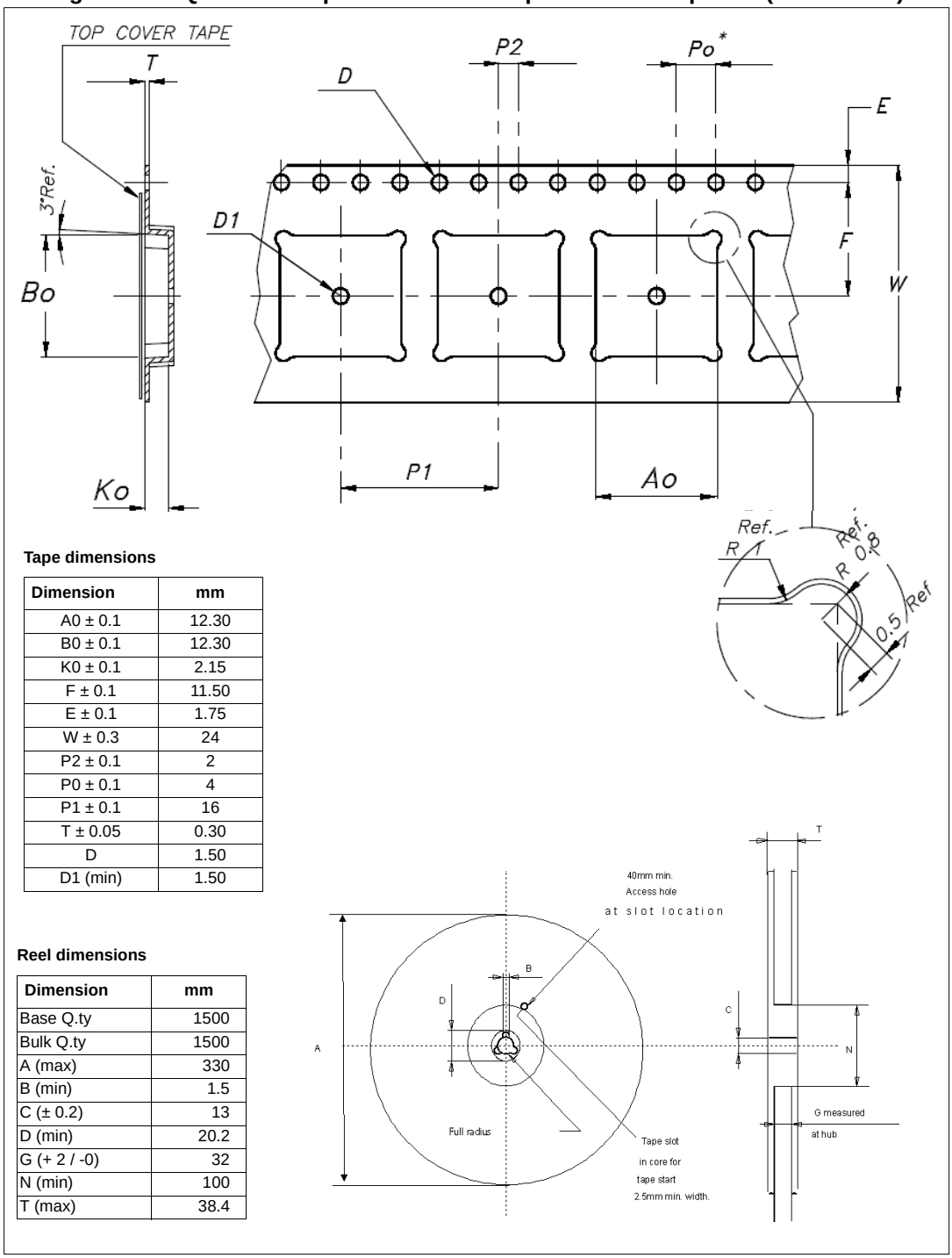
Tray information

Parameter	
Base Q.ty	189
Bulk Q.ty	945

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. ALL DIMENSIONS ARE MILLIMETERS.
2. IDENTIFY WITH APPLICABLE TEMPERATURE CALLOUT AS ORIENTED AND SHOWN.
3. TRAYS MUST STACK WITHOUT STICKING AND WITH 0.13 TO 0.51 MOVEMENT SIDE-TO-SIDE AND END-TO-END.
4. COUNTRY OF ORIGIN.

Figure 37. PQFN - 12x12 power lead-less tape and reel shipment (suffix “TR”)



Tape dimensions

Dimension	mm
A0 ± 0.1	12.30
B0 ± 0.1	12.30
K0 ± 0.1	2.15
F ± 0.1	11.50
E ± 0.1	1.75
W ± 0.3	24
P2 ± 0.1	2
P0 ± 0.1	4
P1 ± 0.1	16
T ± 0.05	0.30
D	1.50
D1 (min)	1.50

Reel dimensions

Dimension	mm
Base Q.ty	1500
Bulk Q.ty	1500
A (max)	330
B (min)	1.5
C (± 0.2)	13
D (min)	20.2
G (+ 2 / -0)	32
N (min)	100
T (max)	38.4

6 Revision history

Table 15. Document revision history

Date	Revision	Changes
13-May-2009	1	Initial release.
19-Sep-2013	2	Updated Disclaimer.
28-Oct-2013	3	Updated footnote 2 into the *Table 8: Electrical transient requirements (part 1/3)* and *Table 9: Electrical transient requirements (part 2/3)*.

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